

### Abstract

According to the invention, the distribution of material amounts deposited on the substrate may be optimized for magnetron sputter coating in which a magnetron magnetic field pattern (9) is cyclically ( $M_y$ ) moved along the sputtering surface (7) and a substrate (11) is passed along the sputter surface (7), whereby the sputter rate is modulated by means of a modulation device (3), phase-locked with the cyclical movement ( $M_7$ ) of the field pattern (9).